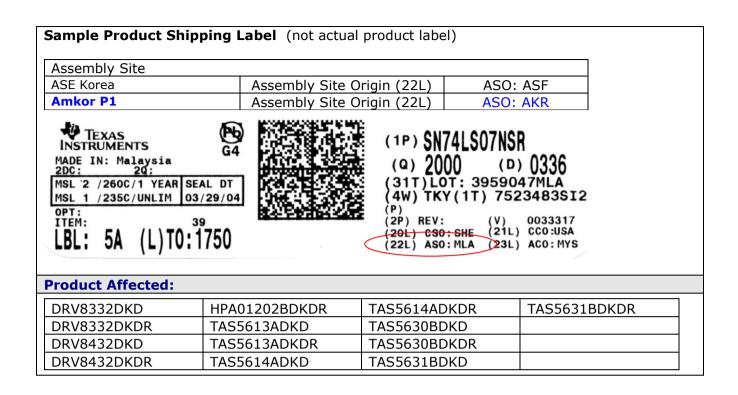
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Assembly Pro		Data Sheet					er Bump Material		
Assembly Mat		Part number change				Wafer Bump Process			
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Qualification Report

Approval Date 9-Nov-2018

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: DRV8432DK DR	QBS Device: TAS5424BTDKDR Q1	QBS Device: TAS5424BTDKE Q1
PC	Preconditioning	Level 4-260C	3/77/0		
TC	Temperature Cycle, -65/150C	500 Cycles	3/77/0		
MQ	Manufacturability (Assembly)	(per mfg. site spec.)	PASS		
MSL	Moisture Sensitivity	Level 4-260C	3/12/0		
YLD	FTY and Bin Summary	-	PASS		
PC	Auto Preconditioning	Level 3-245C		3/321/0	3/398/0
HTSL	Auto High Temperature Storage Life, 150C	1000 Hours		3/135/0	3/135/0
HAST	Auto Biased HAST, 130C/85%RH	96 Hours		3/231/0	3/231/0
AC	Auto Autoclave, 121C, 2 atm	96 Hours		3/231/0	3/231/0
TC	Auto Temperature Cycle, -65/150C	500 Cycles		3/231/0	3/231/0
PTC	Auto Power Temperature Cycle, - 40/105C	500 Cycles		1/45/0	1/45/0
WBP	Auto Post TC Bond Pull			PASS	PASS
MQ	Manufacturability (Auto Assembly)	(per mfg. site spec.)		PASS	PASS
HTOL	Auto High Temperature Operating Life, 125C	1000 Hours			3/231/0
ELFR	Auto Early Life Failure Rate, 150C	24 Hours			3/800/0
ED	Electrical Distributions	Cpk>1.67, tri- temp			3/90/0

SD	Auto Solderability	Pb / Pb-Free	 	1/30/0
PD	Auto Physical Dimensions	(per device drawing)	 	3/30/0
TPI	Thermal Path Integrity	Level 3-245C	 	3/36/0

- QBS: Qual by Similarity

- Qual Device DRV8432DKDR is qualified at LEVEL4-260C.

- QBS Device TAS5424BTDKDRQ1 is qualified at LEVEL3-245C.

- QBS Device TAS5424BTDKEQ1 is qualified at LEVEL3-245C.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable.

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours,

150C/300 Hours, and 155C/240 Hours.

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1000 Hours, and 170C/420 Hours.

- The following are equivalent Temperature Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles.

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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